



**ROHM's Selection Operational Amplifier/Comparator Series** 





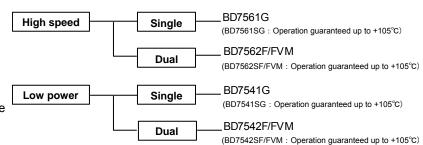
# Operational Amplifiers: High Voltage CMOS

Input-Output Full Swing
 BD7561G,BD7561SG,BD7541G,BD7541SG,
 BD7562F/FVM,BD7562S F/FVM, BD7542F/FVM,BD7542S F/FVM

### Description

High voltage operable CMOS Op-Amp BD7561/BD7541 family and BD7562/BD7542 family Integrate one or two independent input-output full swing Op-amps and phase compesation capacitors on a single chip.

Especially, characteristics are wide operating voltage range of +5[V]~+14.5[V](single power supply), low supply current and little input bias current.



### Characteristics

- 1) Wide operating supply voltage( $+5[V] \sim +14.5[V]$ )
- 2)  $+5[V]\sim+14.5[V]$ (single supply)  $\pm2.5[V]\sim\pm7.25[V]$ (split supply)
- 3) Input and Output full swing
- 4) Internal phase compensation
- 5) High slew rate (BD7561 family, BD7562 family)
- 6) Low supply current (BD7541 family, BD7542 family)
- 7) High large signal voltage gain

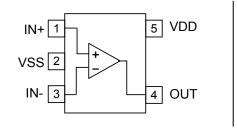
- Internal ESD protection
   Human body model (HBM) ±4000[V](Typ.)
- Wide temperature range
  - -40[°C]~+85[°C]

(BD7561G,BD7562 family, BD7541G,BD7542 family)

 $-40[^{\circ}C] \sim +105[^{\circ}C]$ 

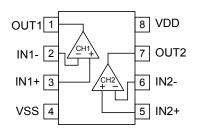
(BD7561SG,BD7562S family, BD7541SG,BD7542S family)

### ●Pin Assignment



BD7561G BD7561SG BD7541G BD7541SG

SSOP5



SOP8	M SOP8
BD7562F	BD7562FVM
	22.002
BD7562SF	BD7562SFVM
BD7542F	BD7542FVM
BD7542SF	BD7542SFVM

Dec. 2008

Absolute Maximum Ratings (Ta=25[°C])

		Rati								
Parameter	Symbol	BD7561G, BD7562 F/FVM	BD7561SG, BD7562S F/FVM	Unit						
		BD7541G, BD7542 F/FVM	BD7541SG, BD7542S F/FVM							
Supply Voltage	VDD-VSS	+ 1:	+15.5							
Differential Input Voltage(*1)	Vid	VDD-VSS								
Input Common-mode Voltage Range	Vicm	(VSS−0.3)~	(VSS−0.3)~(VDD+0.3)							
Operating Temperature	Topr	-40~+85	-40~+85 -40~+105							
Storage Temperature	Tstg	<b>−55∼+125</b>								
Maximum Junction Temperature	Tjmax	+125								

### Electric Characteristics

○BD7561 family. BD7562 family (Unless otherwise specified VDD=+12[V1, VSS=0[V1, Ta=25[°C1)

					Guaran	teed limit					
Parameter	Symbol	Temperature range	BD7561G BD7561SG			BD7562 F/FVM BD7562S F/FVM			Unit	Condition	
		_	Min.	Тур.	Max.	Min.	Тур.	Max.			
Input Offset Voltage (*2)(*4)	Vio	25℃	-	1	9	-	1	9	mV	VDD=5~14.5[V],VOUT=VDD/2	
	VIO	Full range	-	-	10	-	-	10	IIIV	VDD-5° = 14.5[v], VOO 1 = VDD/2	
Input Offset Current (*2)	lio	25℃	-	1	-	-	1	-	pА	-	
Input Bias Current (*2)	lb	25℃	-	1	-	-	1	-	pА	-	
Supply Current (*4)		25℃	-	370	550	-	750	1300		RL=∞ All Op-Amps	
	IDD	Full range	-	-	600	-	-	1500	μA	AV=0[dB],VDD=5[V],VIN=2.5[V]	
	טטו	25℃	-	440	650	-	900	1400	μΑ	RL=∞ All Op-Amps	
		Full range	-	-	700	-	-	1600		AV=0[dB],VDD=12[V],VIN=6.0[V]	
High Level Output Voltage	VOH	25℃	VDD-0.1	-	-	VDD-0.1	-	-	V	RL=10[kΩ]	
Low Level Output Voltage	VOL	25℃	-	-	VSS+0.1	-	-	VSS+0.1	V	RL=10[kΩ]	
Large Single Voltage Gain	AV	25℃	70	95	-	70	95	-	dB	RL=10[kΩ]	
Input Common-mode Voltage Range	Vicm	25℃	0	-	12	0	-	12	V	VDD-VSS=12[V]	
Common-mode Rejection Ratio	CMRR	25℃	45	60	-	45	60	-	dB	-	
Power Supply Rejection Ratio	PSRR	25℃	60	80	-	60	80	-	dB	-	
Output Source Current (*3)	IOH	25℃	3	8	-	3	8	-	mΑ	VDD-0.4[V]	
Output Sink Current (*3)	IOL	25℃	4	14	-	4	14	-	mA	VSS+0.4[V]	
Slew Rate	SR	25℃	-	0.9	-	-	0.9	-	V/µs	CL=25[pF]	
Gain Bandwidth Product	FT	25℃	-	1.0	-	-	1.0	-	MHz	CL=25[pF], AV=40[dB]	
Phase Margin	θ	25℃	-	50°	-	-	50°	-	_	CL=25[pF], AV=40[dB]	
Total Harmonic Distortion	THD	25℃	-	0.05	-	-	0.05	-	%	VOUT=1[Vp-p],f=1[kHz]	

### Electric Characteristics

○BD7541 family, BD7542 family (Unless otherwise specified VDD=+12[V], VSS=0[V], Ta=25[°C])

				Guaran	teed limit					
Parameter	Symbol	Temperature range	BD7541G BD7541SG			BD7542 F/FVM BD7542S F/FVM			Unit	Condition
		_	Min.	Тур.	Max.	Min.	Тур.	Max.		
Input Offset Voltage (*5)(*7)	Vio	25℃	-	1	9	-	1	9	mV	VDD=5~14.5[V],VOUT=VDD/2
	VIO	Full range	-	-	10	-	-	10	IIIV	VDD-5° = 14.5[V], VOO 1 = VDD/2
Input Offset Current (*5)	lio	25℃	-	1	-	-	1	-	pА	-
Input Bias Current (*5)	lb	25℃	-	1	-	-	1	-	pА	-
Supply Current (*7)		25℃	-	170	300	-	340	650		RL=∞ All Op-Amps
	IDD	Full range	-	-	400	-	-	850		AV=0[dB],VDD=5[V],VIN=2.5[V]
	טטו	25℃	-	180	320	-	400	780	μA	RL=∞ All Op-Amps
		Full range	-	-	420	-	-	900		AV=0[dB],VDD=12[V],VIN=6.0[V]
High Level Output Voltage	VOH	25℃	VDD-0.1	-	-	VDD-0.1	-	-	V	RL=10[kΩ]
Low Level Output Voltage	VOL	25℃	-	-	VSS+0.1	-	-	VSS+0.1	V	RL=10[kΩ]
Large Single Voltage Gain	AV	25℃	70	95	-	70	95	-	dB	RL=10[kΩ]
Input Common-mode Voltage Range	Vicm	25℃	0	-	12	0	-	12	V	VDD-VSS=12[V]
Common-mode Rejection Ratio	CMRR	25℃	45	60	-	45	60	-	dB	-
Power Supply Rejection Ratio	PSRR	25℃	60	80	-	60	80	-	dB	-
Output Source Current (*6)	IOH	25℃	2	4	-	2	4	-	mA	VDD-0.4[V]
Output Sink Current (*6)	IOL	25℃	3	7	-	3	7	-	mA	VSS+0.4[V]
Slew Rate	SR	25℃	-	0.3	-	-	0.3	-	V/µs	CL=25[pF]
Gain Bandwidth Product	FT	25℃	-	0.6	-	-	0.6	-	MHz	CL=25[pF], AV=40[dB]
Phase Margin	θ	25℃	-	50°	-	-	50°	-	_	CL=25[pF], AV=40[dB]
Total Harmonic Distortion	THD	25℃	-	0.05	-	-	0.05	-	%	VOUT=1[Vp-p],f=1[kHz]

Absolute value

Note: Absolute maximum rating item indicates the condition which must not be exceeded.

Application of voltage in excess of absolute maximum rating or use out absoluted maximum rated temperature environment may cause deterioration of characteristics.

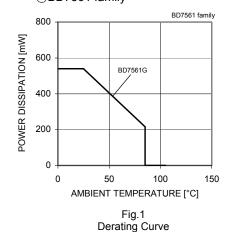
(\*1) The voltage difference between inverting input and non-inverting input is the differential input voltage.

Then input terminal voltage is set to more then VSS.

 <sup>(\*2)</sup> Absolute value
 (\*3) Under the high temperature environment, consider the power dissipation of IC when selecting the output current. When the terminal short circuits are continuously output, the output current is reduced to climb to the temperature inside IC.
 (\*4) Full range: BD7561, BD7562: Ta=-40[°C]~+85[°C] BD7561S, BD7562S: Ta=-40[°C]~+105[°C]

 <sup>(\*6)</sup> Under the high temperature environment, consider the power dissipation of IC when selecting the output current.
 When the terminal short circuits are continuously output, the output current is reduced to climb to the temperature inside IC.
 (\*7) Full range: BD7541, BD7542: Ta=-40[°C]~+85[°C] BD7541S, BD7542S: Ta=-40[°C]~+105[°C]

### Example of electrical characteristics ○BD7561 family



BD7561 family 800 SUPPLY CURRENT [µA] 14.5\ 600 400

200

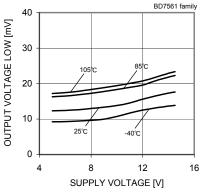
0

-60 -30 0

Fig.4 Supply Current - Ambient Temperature

30 60 90 120

AMBIENT TEMPERATURE [°C]



Output Voltage Low - Supply Voltage (RL=10[kΩ])

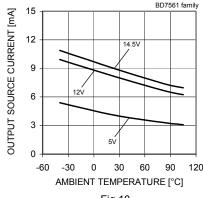


Fig.10 Output Source Current - Ambient Temperature (VOUT=VDD-0.4[V])

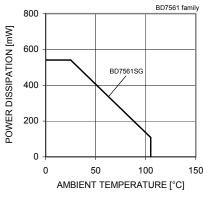
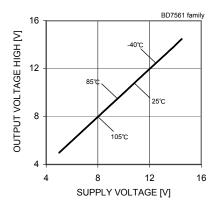


Fig.2 Derating Curve



Output Voltage High - Supply Voltage  $(RL=10[k\Omega])$ 

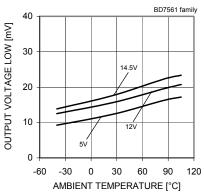


Fig.8 Output Voltage Low - Ambient Temperature  $(RL=10[k\Omega])$ 

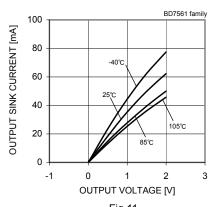
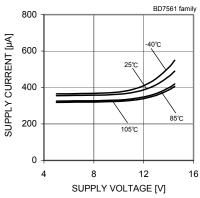


Fig.11 Output Sink Current - Output Voltage (VDD=12[V])



Supply Current - Supply Voltage

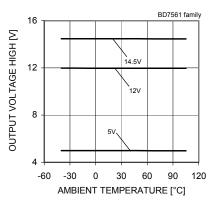


Fig.6 Output Voltage High - Ambient Temperature  $(RL=10[k\Omega])$ 

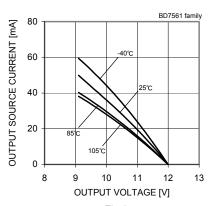
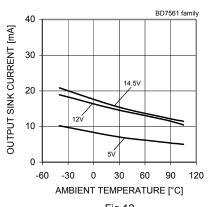
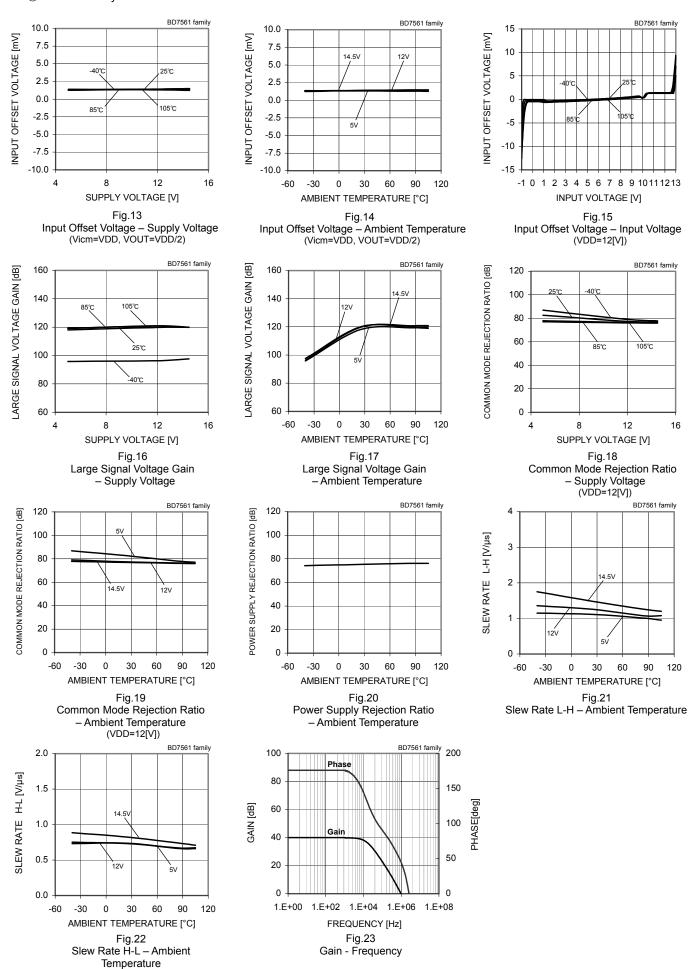


Fig.9 Output Source Current - Output Voltage (VDD=12[V])



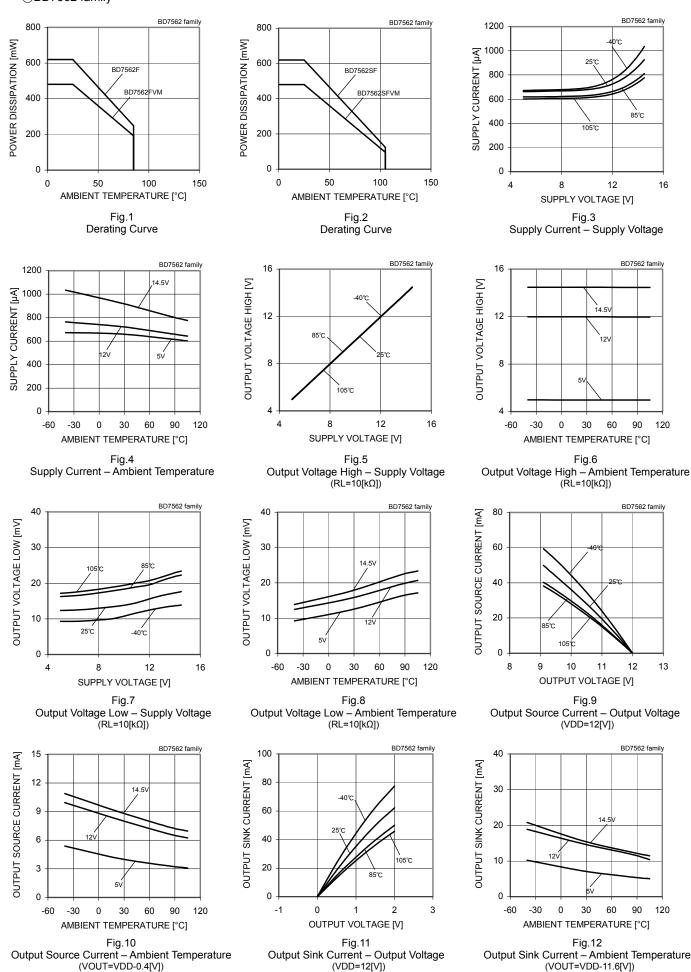
Output Sink Current - Ambient Temperature (VOUT=VDD-11.6[V])

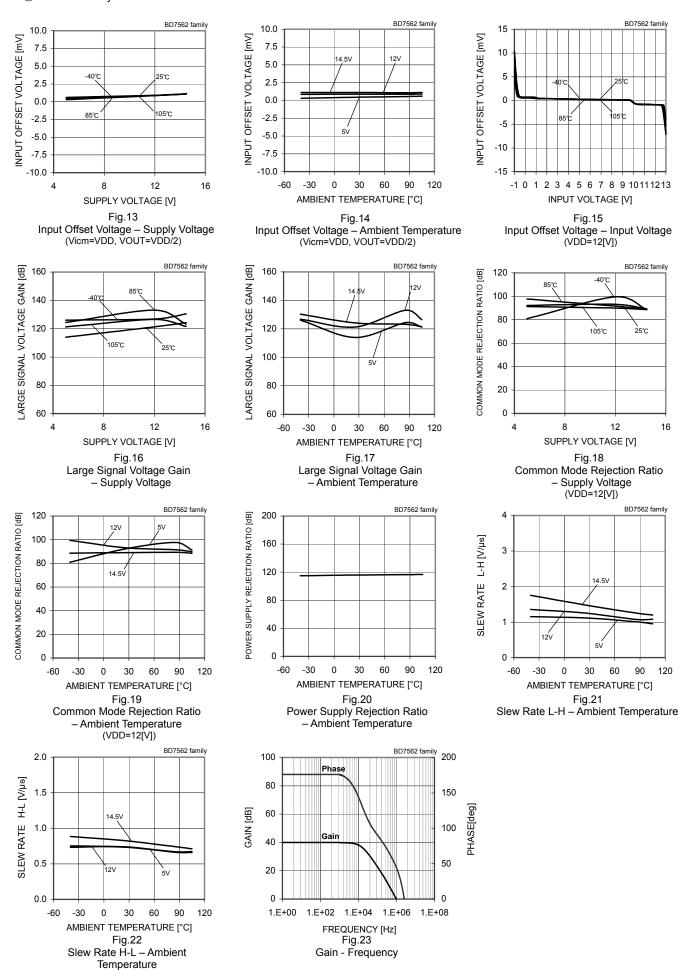
### ○BD7561 family



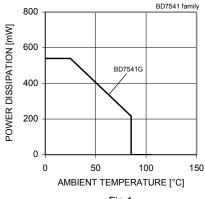
(\*)The above data is ability value of sample, it is not guaranteed. BD7561: -40[℃]~+85[℃] BD7561S: -40[℃]~+105[℃]

### ●Example of electrical characteristics ○BD7562 family





# ●Example of electrical characteristics ○BD7541 family



800 BD7541 family
NOLLY 400
BD7541SG
BD7541SG
BD7541SG
BD7541SG
AMBIENT TEMPERATURE [°C]

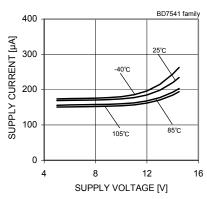
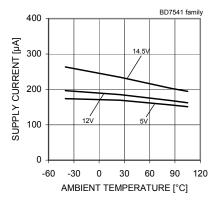
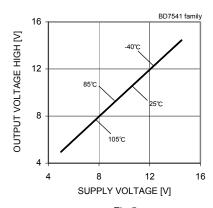


Fig.1 Derating Curve



Fig.3 Supply Current – Supply Voltage





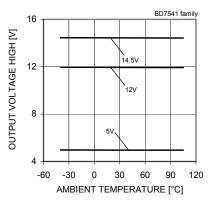
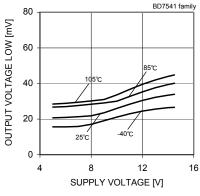
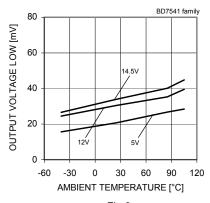


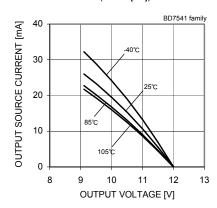
Fig.4
Supply Current – Ambient Temperature

Fig.5 Output Voltage High – Supply Voltage  $(RL=10[k\Omega])$ 

Fig.6
Output Voltage High – Ambient Temperature  $(RL=10[k\Omega])$ 



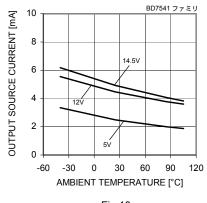


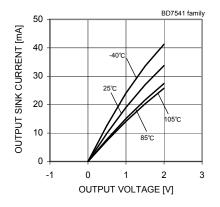


 $\begin{array}{c} Fig.7 \\ Output \ Voltage \ Low - Supply \ Voltage \\ (RL=10[k\Omega]) \end{array}$ 

 $\begin{array}{c} Fig.8 \\ Output \ Voltage \ Low - Ambient \ Temperature \\ (RL=10[k\Omega]) \end{array}$ 

Fig.9
Output Source Current – Output Voltage (VDD=12[V])





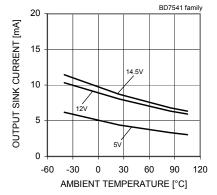
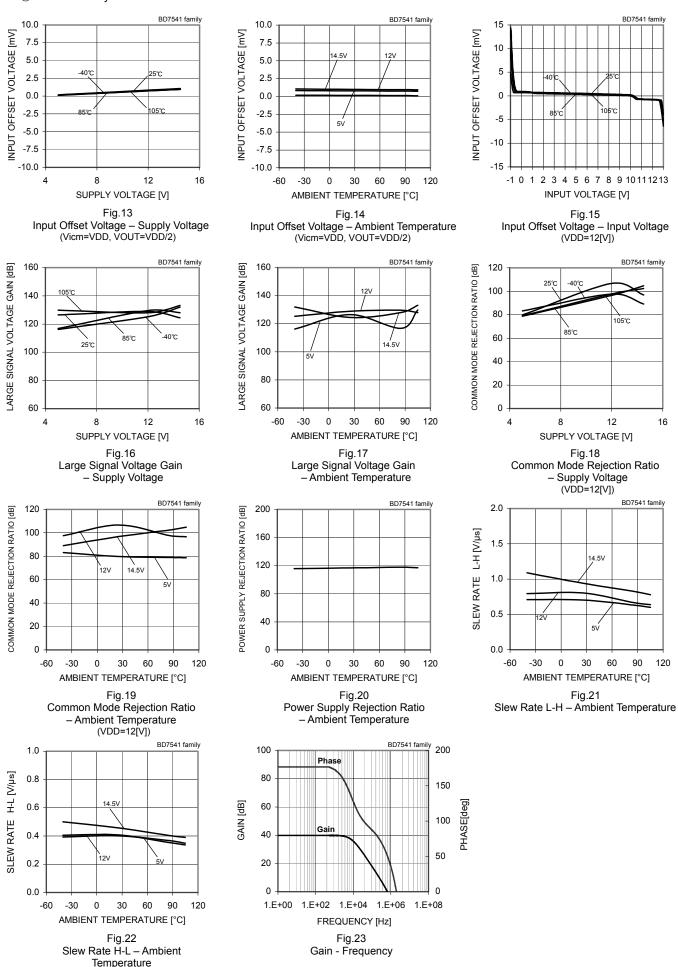


Fig.10
Output Source Current – Ambient Temperature
(VOUT=VDD-0.4[V])

Fig.11
Output Sink Current – Output Voltage (VDD=12[V])

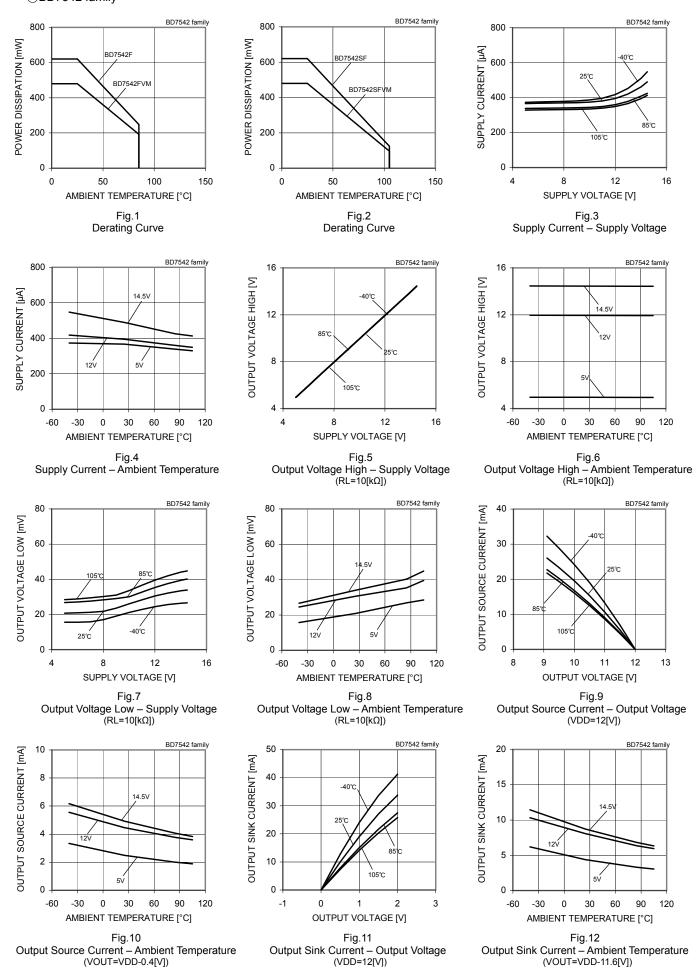
Fig.12
Output Sink Current – Ambient Temperature
(VOUT=VDD-11.6[V])

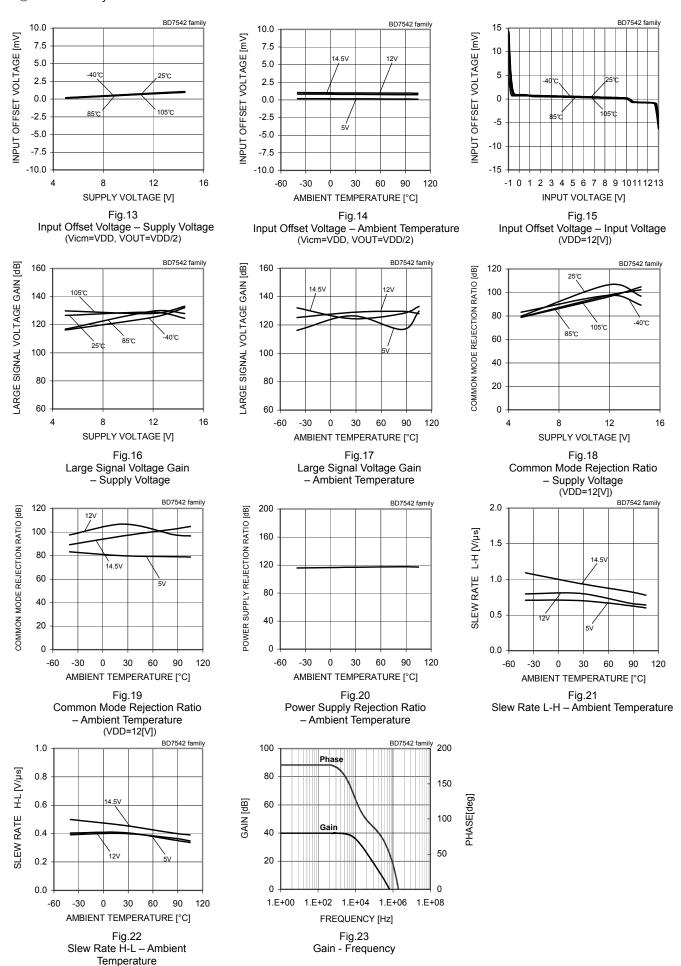
### ○BD7541 family



 $(*) The above data is ability value of sample, it is not guaranteed. BD7541: -40[^{\circ}C] \\ \sim +85[^{\circ}C] \\ BD7541S: -40[^{\circ}C] \\ \sim +105[^{\circ}C] \\ \sim +105[^{\circ}C]$ 

### ●Example of electrical characteristics ○BD7542 family





### Schematic diagram

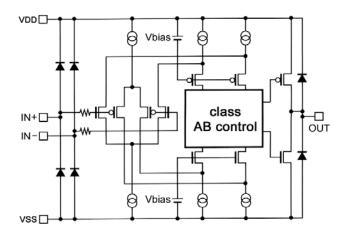


Fig1. Schematic diagram

# ●Test circuit1 NULL method

VDD, VSS, EK, Vicm Unit: [V]

Parameter	VF	S1	S2	S3	VDD	VSS	EK	Vicm	Calculation
Input Offset Voltage	VF1	ON	ON	OFF	12	0	-6	12	1
Large Signal Voltage Gain	VF2	ON	ON	ON	12	0	-0.5	6	2
	VF3						-11.5		
Common-mode Rejection Ratio	VF4	ON	ON	OFF	12	0	-6	0	3
(Input Common-mode Voltage Range)	VF5	ON						12	
Dower Supply Pointing Potic	VF6	ON	ON	OFF	5	0	2.5	0	4
Power Supply Rejection Ratio	VF7	ON	ON	UFF	14.5	0	-2.5	0	4

- $-{\sf Calculation} -$
- 1. Input Offset Voltage (Vio)

$$Vio = \frac{|VF1|}{1 + Rf/Rs} [V]$$

2. Large Signal Voltage Gain (Av)

$$Av = 20Log \frac{2 \times (1 + Rf/Rs)}{|VF2 - VF3|} \quad [dB]$$

3. Common-mode Rejection Ratio (CMRR)

$$CMRR = 20Log \frac{1.8 \times (1 + Rf/Rs)}{|VF4-VF5|} [dB]$$

4. Power Supply Rejection Ratio (PSRR)

$$PSRR = 20Log \frac{3.8 \times (1 + Rf/Rs)}{|VF6-VF7|} [dB]$$

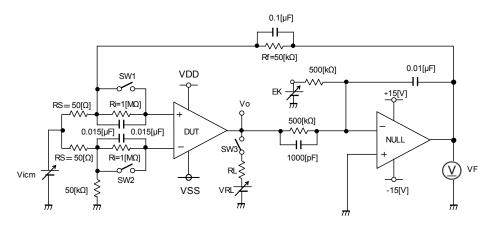


Fig.2 Test circuit 1 (one channel only)

# ●Test circuit2 switch condition

Unit: [V]

*[.]												
SW No.	SW 1	SW 2	SW 3	SW 4	SW 5	SW 6	SW 7	SW 8	SW 9	SW 10	SW 11	SW 12
Supply Current	OFF	OFF	ON	OFF	ON	OFF	OFF	OFF	OFF	OFF	OFF	OFF
Maximum Output Voltage RL=10 [kΩ]	OFF	ON	OFF	OFF	ON	OFF	OFF	ON	OFF	OFF	ON	OFF
Output Current	OFF	ON	OFF	OFF	ON	OFF	OFF	OFF	OFF	ON	OFF	OFF
Slew Rate	OFF	OFF	ON	OFF	OFF	OFF	ON	OFF	ON	OFF	OFF	ON
Maximum Frequency	ON	OFF	OFF	ON	ON	OFF	OFF	OFF	ON	OFF	OFF	ON

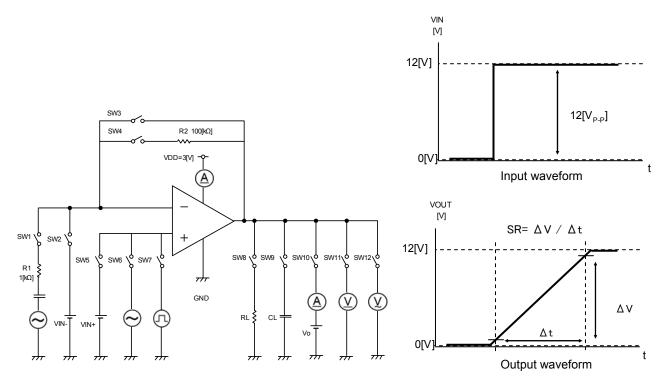


Fig3. Test circuit2

Fig4. Slew rate input output wave

# ●Test circuit3 Channel separation

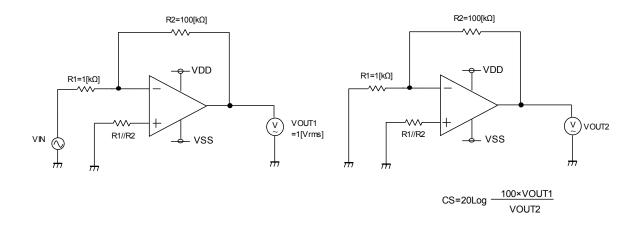


Fig5. Test circuit3

### Description of electrical characteristics

Described here are the terms of electric characteristics used in this technical note. Items and symbols used are also shown. Note that item name and symbol and their meaning may differ from those on another manufacture's document or general document.

### Absolute maximum ratings

Absolute maximum rating item indicates the condition which must not be exceeded. Application of voltage in excess of absolute maximum rating or use out of absolute maximum rated temperature environment may cause deterioration of characteristics.

### 1.1 Power supply voltage (VDD/VSS)

Indicates the maximum voltage that can be applied between the positive power supply terminal and negative power supply terminal without deterioration or destruction of characteristics of internal circuit.

### Differential input voltage (Vid)

Indicates the maximum voltage that can be applied between non-inverting terminal and inverting terminal without deterioration and destruction of characteristics of IC.

### 13 Input common-mode voltage range (Vicm)

Indicates the maximum voltage that can be applied to non-inverting terminal and inverting terminal without deterioration or destruction of characteristics. Input common-mode voltage range of the maximum ratings not assure normal operation of IC. When normal Operation of IC is desired, the input common-mode voltage of characteristics item must be followed.

### Power dissipation (Pd)

Indicates the power that can be consumed by specified mounted board at the ambient temperature 25°C (normal temperature). As for package product, Pd is determined by the temperature that can be permitted by IC chip in the package (maximum junction temperature) and thermal resistance of the package.

### Electrical characteristics item

### 2.1 Input offset voltage (Vio)

Indicates the voltage difference between non-inverting terminal and inverting terminal. It can be translated into the input voltage difference required for setting the output voltage at 0 [V].

### 2.2

Indicates the difference of input bias current between non-inverting terminal and inverting terminal.

### 2.3

Indicates the current that flows into or out of the input terminal. It is defined by the average of input bias current at non-inverting terminal and input bias current at inverting terminal.

### 2.4 Circuit current (ICC)

Indicates the IC current that flows under specified conditions and no-load steady status.

### High level output voltage / Low level output voltage (VOH/VOL) 2.5

Indicates the voltage range that can be output by the IC under specified load condition. It is typically divided into high-level output voltage and low-level output voltage. High-level output voltage indicates the upper limit of output voltage. Low-level output voltage indicates the lower limit.

### 2.6

Large signal voltage gain (AV)
Indicates the amplifying rate (gain) of output voltage against the voltage difference between non-inverting terminal and inverting terminal. It is normally the amplifying rate (gain) with reference to DC voltage.

Av = (Output voltage fluctuation) / (Input offset fluctuation)

### 27 Input common-mode voltage range (Vicm)

Indicates the input voltage range where IC operates normally.

### 2.8 Common-mode rejection ratio (CMRR)

Indicates the ratio of fluctuation of input offset voltage when in-phase input voltage is changed. It is normally the fluctuation of DC. CMRR = (Change of Input common-mode voltage) / (Input offset fluctuation)

### 2.9 Power supply rejection ratio (PSRR)

Indicates the ratio of fluctuation of input offset voltage when supply voltage is changed. It is normally the fluctuation of DC. PSRR= (Change of power supply voltage) / (Input offset fluctuation)

### 2.10 Channel separation (CS)

Indicates the fluctuation of input offset voltage or that of output voltage with reference to the change of output voltage of driven channel.

Indicates the time fluctuation ratio of voltage output when step input signal is applied.

# 2.12 Unity gain frequency (ft)

Indicates a frequency where the voltage gain of Op-Amp is 1.

### 2.13 Total harmonic distortion + Noise (THD+N)

Indicates the fluctuation of input offset voltage or that of output voltage with reference to the change of output voltage of driven channel.

### 2.14 Input referred noise voltage (Vn)

Indicates a noise voltage generated inside the operational amplifier equivalent by ideal voltage source connected in series with input terminal.

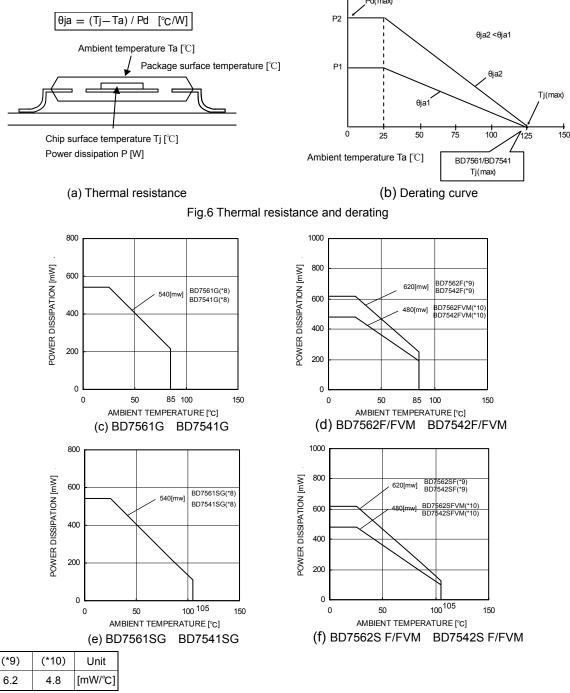
### Derating curve

Power dissipation (total loss) indicates the power that can be consumed by IC at  $Ta=25^{\circ}C$  (normal temperature).IC is heated when it consumed power, and the temperature of IC ship becomes higher than ambient temperature. The temperature that can be accepted by IC chip depends on circuit configuration, manufacturing process, and consumable power is limited. Power dissipation is determined by the temperature allowed in IC chip (maximum junction temperature) and thermal resistance of package (heat dissipation capability). The maximum junction temperature is typically equal to the maximum value in the storage temperature range. Heat generated by consumed power of IC radiates from the mold resin or lead frame of the package. The parameter which indicates this heat dissipation capability (hardness of heat release) is called thermal resistance, represented by the symbol  $\theta_j$ -a[ ${^{\circ}C/W}$ ]. The temperature of IC inside the package can be estimated by this thermal resistance. Fig.6 (a) shows the model of thermal resistance of the package. Thermal resistance  $\theta_j$ , ambient temperature Ta, junction temperature Tj, and power dissipation Pd can be calculated by the equation below:

$$\theta$$
ja =  $(Tj-Ta)/Pd$  [ $^{\circ}C/W$ ]  $\cdots \cdots$  (1)

Derating curve in Fig.6 (b) indicates power that can be consumed by IC with reference to ambient temperature. Power that can be consumed by IC begins to attenuate at certain ambient temperature. This gradient iis determined by thermal resistance  $\theta$ ja. Thermal resistance  $\theta$ ja depends on chip size, power consumption, package, ambient temperature, package condition, wind velocity, etc even when the same of package is used. Thermal reduction curve indicates a reference value measured at a specified condition. Fig7(c)-(f) show a derating curve for an example of BU7561family, BU7562family, 7541family, 7542family.

Power dissipation of LSI [W]



When using the unit above  $Ta=25[^{\circ}C]$ , subtract the value above per degree[ $^{\circ}C$ ]. Permissible dissipation is the value when FR4 glass epoxy board  $T0[mm] \times T0[mm] \times 1.6[mm]$  (cooper foil area below 3[%]) is mounted.

(\*8)

### Cautions on use

### 1) Absolute maximum ratings

Absolute maximum ratings are the values which indicate the limits, within which the given voltage range can be safely charged to the terminal. However, it does not guarantee the circuit operation.

### 2) Applied voltage to the input terminal

For normal circuit operation of voltage comparator, please input voltage for its input terminal within input common mode voltage VDD+0.3[V]. Then, regardless of power supply voltage,VSS-0.3[V] can be applied to input terminals without deterioration or destruction of its characteristics.

### 3) Operating power supply (split power supply/single power supply)

The voltage comparator operates if a given level of voltage is applied between VDD and VSS. Therefore, the operational amplifier can be operated under single power supply or split power supply.

### 4) Power dissipation (Pd)

If the IC is used under excessive power dissipation. An increase in the chip temperature will cause deterioration of the radical characteristics of IC.

For example, reduction of current capability. Take consideration of the effective power dissipation and thermal design with a sufficient margin. Pd is reference to the provided power dissipation curve.

### 5) Short circuits between pins and incorrect mounting

Short circuits between pins and incorrect mounting when mounting the IC on a printed circuits board, take notice of the direction and positioning of the IC.

If IC is mounted erroneously, It may be damaged. Also, when a foreign object is inserted between output, between output and VDD terminal or VSS terminal which causes short circuit, the IC may be damaged.

### 6) Using under strong electromagnetic field

Be careful when using the IC under strong electromagnetic field because it may malfunction.

### 7) Usage of IC

When stress is applied to the IC through warp of the printed circuit board,

The characteristics may fluctuate due to the piezo effect.

Be careful of the warp of the printed circuit board.

### 8) Testing IC on the set board

When testing IC on the set board, in cases where the capacitor is connected to the low impedance, make sure to discharge per fabrication because there is a possibility that IC may be damaged by stress. When removing IC from the set board, it is essential to cut supply voltage.

As a countermeasure against the static electricity, observe proper grounding during fabrication process and take due care when carrying and storage it.

### 9) The IC destruction caused by capacitive load

The transistors in circuits may be damaged when VDD terminal and VSS terminal is shorted with the charged output terminal capacitor. When IC is used as a operational amplifier or as an application circuit, where oscillation is not activated by an output capacitor, the output capacitor must be kept below  $0.1[\mu F]$  in order to prevent the damage mentioned above.

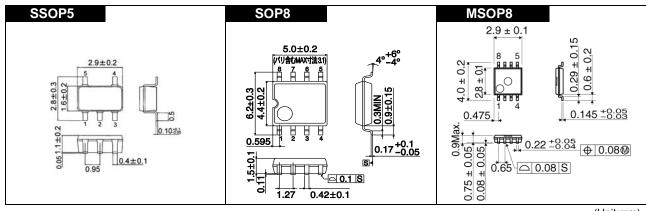
### 10) Decupling capacitor

Insert the deculing capacitance between VDD and VSS, for stable operation of operational amplifier.

### 11) Latch up

Be careful of input vltage that exceed the VDD and VSS. When CMOS device have sometimes occur latch up operation. And protect the IC from abnormaly noise.

### Dimensions



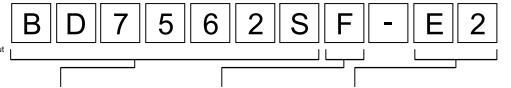
# Model number construction

(Unit:mm)

E2 Embossed tape on reel with pin 1 near far when pulled out TR Embossed tape on reel with pin 1 near far when pulled out

- · Specify the product by the model
- number when placing an order.

  Make sure of the combinations of items.
- Start with the leftmost space without leaving any empty space between characters.



### **Product name**

- BD7561 BD7561S

: SSOP5 : SOP8

Package type

• BD7541 **BD7541S** · BD7562 BD7562S

• FVM: MSOP8

BD7542 **BD7542S** 

# Packing specification reference

Package	Packing specification name	Quantity	Embossed carrier tape
SSOP5	TR	3000	1Pin Direction of feed
SOP8	E2	2500	Real 1Pin Direction of feed
MSOP8	TR	3000	Pin Direction of feed

\*When you order, please order in times the amount of package quantity.

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